

# AN-2231 LM3492HC Evaluation Board Reference Design

#### 1 Introduction

The LM3492HC integrates a boost converter and a two-channel current regulator to implement a high efficient and cost effective LED driver for driving two individually dimmable LED strings with a maximum power of 15W and an output voltage of up to 65V. The boost converter employs a proprietary Projected-On-Time control method to give a fast transient response with no compensation required, and a nearly constant switching frequency programmable from 200 kHz to 1 MHz. The application circuit is stable with ceramic capacitors and produces no audible noise on dimming. The programmable peak current limit and soft-start features reduce current surges at startup, and an integrated 190 m $\Omega$ , 3.9A N-Channel MOSFET switch minimizes the solution size. The fast slew rate current regulator allows high frequency and narrow pulse width dimming signals to achieve a very high contrast ratio of 10000:1 at a dimming frequency of 200Hz. The LED current is programmable from 50 mA to 250 mA by a single resistor.

To maximize the efficiency, Dynamic Headroom Control (DHC) automatically adjusts the output voltage to a minimum. To increase the contrast ratio, the DHC can be over-ridded when the contrast ratio is high. DHC also facilitates a single BOM for different number of LED in a string, which is required for backlight panels of different size, thereby reducing overall development time and cost. The LM3492HC comes with a versatile COMM pin which serves as a bi-directional I/O pin interfacing with an external MCU for the following functions: power-good, over-temperature, IOUT over- and under-voltage indications, switching frequency tuning, and channel 1 disabling. Other supervisory functions of the LM3492HC include precise enable, VCC under-voltage lock-out, current regulator Over-Power protection, and thermal shutdown protection. The LM3492HC is available in the thermally enhanced HTSSOP-20 package.

This application note details the design of a LM3492HC evaluation board which drives two LED strings, each of which consists of 10 LEDs running at 150 mA and the forward voltage of each LED is typically 3.8V. The input voltage is from 9V to 16V. The evaluation board schematic, PCB layout, Bill of Materials, and circuit design descriptions are shown. Typical performance and operating waveforms are also provided for reference.



# 2 Evaluation Board Schematic and PCB Layout

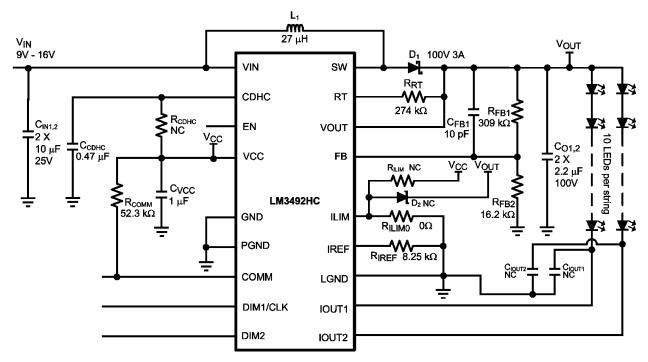


Figure 1. LM3492HC Evaluation Board Schematic

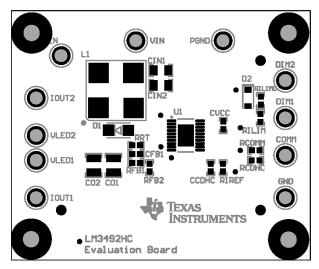
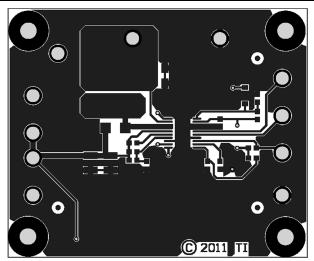


Figure 2. LM3492HC Evaluation Board Top Overlay





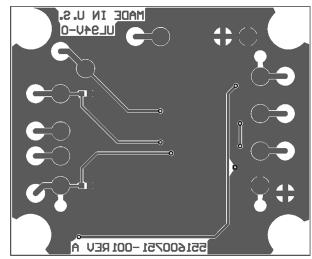


Figure 3. LM3492HC Evaluation Board Top View

Figure 4. LM3492HC Evaluation Board Bottom View

**Table 1. Evaluation Board Quick Setup Procedures** 

Step	Description	Notes
1	Connect a power supply to VIN and PGND terminals	V <sub>IN</sub> range: 9V to 16V
2	Connect 2 LED strings: from VLED1 to IOUT1 terminals, and VLED2 to IOUT2 terminals	Each LED string consists of 10 LEDs with a forward voltage of 3.8V per LED at 150 mA
3	The EN terminal should be left open for normal operation.  Ground this terminal to shutdown	
4	Connect DIM1 and DIM2 terminals to a voltage > 2V, apply $V_{\text{IN}} = 12V$	Nominal LED current is 150 mA per channel
5	Ground the EN terminal to check the shutdown function	

**Table 2. Evaluation Board Performance Characteristic** 

Description	Symbol	Condition	Min	Тур	Max	Unit
Input Voltage	V <sub>IN</sub>		9	12	16	V
Rail Voltage	V <sub>OUT</sub>			39		V
LED Current	I <sub>LED</sub>			150		mA
LED Current Regulationt	$\Delta I_{LED}$	ALL V <sub>IN</sub> conditions	-3		+3	%
		$V_{IN} = 9V$		86.3		%
Efficiency		V <sub>IN</sub> = 12V		88.9		%
		V <sub>IN</sub> = 16V		89.8		%



Design Procedure www.ti.com

# 3 Design Procedure

The following procedures detail the design of the LM3492HC evaluation board driving 2 LED strings consists of 10 LEDs per string. The forward voltage of each LED is 3.8V, and the LED current is 150 mA. The input voltage is ranged from 9V to 16V. The switching frequency f<sub>SW</sub> is designed to be 500 kHz.

## **Design Parameters:**

 $V_{IN} = 9V$  to 16V, typical 12V

 $I_{LED} = 150 \text{ mA}$ 

## Step 1: Calculate the output voltage feedback circuit

The nominal voltage of the LED string with 10 LEDs is 38V, and the minimum voltage of the IOUTn pin (n = 1, 2) is 0.75V for an  $I_{LED}$  of 150 mA. Hence,  $V_{OUT(NOM)}$  is 38.75V. We design  $V_{OUT}$  to be 50V when  $V_{FB}$  is 2.5V. Then at  $V_{OUT(NOM)}$ ,  $V_{FB(NOM)}$  is about 1.95V, which is within the suggested dynamic range of  $V_{FB}$  under DHC (from 1.05V to 2V). By designing  $R_{FB2}$  to be 16.2 k $\Omega$ ,  $R_{FB1}$  is calculated as follows:

$$R_{FB1} = R_{FB2}((V_{OUT(MAX)}/2.5V) - 1)$$
(1)

 $R_{\text{FB1}}$  is calculated to be 307.8 k $\Omega$ , and a standard resistor value of 309 k $\Omega$  is selected.  $C_{\text{FB1}}$  is selected to be 10 pF as recommended.

# Step 2: Determine the inductance

The main parameter affected by the inductor is the peak to peak inductor current ripple ( $I_{LR}$ ). To maintain a continuous conduction mode (CCM) operation, the average inductor current  $I_{L1}$  should be larger than half of  $I_{LR}$ .

For a boost converter,  $I_{L1}$  equals to the input current  $I_{IN}$ . The minimum  $I_{IN}$  occurs when  $V_{IN}$  is maximum, which is 16V in this example, and only 1 LED string is turned on (the 2 LED strings are individually dimmable). Hence,

$$I_{IN(MIN)} = (V_{OUT(NOM)} \times I_{LED}) / V_{IN(MAX)}$$
(2)

Also

$$t_{on} = (1 - V_{IN}/V_{OUT}) / f_{SW}$$
 (3)

To ensure a CCM operation,

$$L_{1} = \left(V_{\text{IN(MAX)}} \times t_{\text{on}}\right) / 2I_{\text{IN(MIN)}} \tag{4}$$

It can be calculated that  $I_{IN(MIN)}$ ,  $t_{on}$ , and  $L_1$  are 0.363A, 1.17  $\mu$ s, and 25.8  $\mu$ H. On the other hand,  $I_{IN}$  is maximum when  $V_{IN}$  is minimum, which is 9V in this example, and 2 LED strings are turned on. Hence  $I_{IN(MAX)}$  is 1.29A. From (3),  $t_{on}$  is 1.54  $\mu$ s when  $V_{IN}$  is 9V. Then  $I_{LR}$  is

$$I_{LR} = (V_{IN} \times t_{on}) / L_1 \tag{5}$$

From (5),  $I_{LR}$  is 0.53A. The steady state peak inductor current  $I_{L1(PEAK)}$  is

$$I_{L_1(PEAK)} = I_{L_1} + I_{L_R} / 2$$
 (6)

As a result,  $I_{L1(PEAK)}$  is 1.56A. A standard value of 27  $\mu H$  is selected for  $L_1$ , and the saturation current of  $L_1$  should be larger than 1.56A.

#### Step 3: Determine the diode

The selection of the boost diode  $D_1$  depends on two factors. The first factor is the reverse voltage, which equals to  $V_{OUT}$  in a boost converter. The second factor is the peak diode current at the steady state, which equals to the peak inductor current as shown in (6). In this example, a 100V 3A schottky diode is selected.

#### Step 4: Determine the value of other components

 $C_{IN}$  and  $C_{OUT}$ : The function of the input capacitor  $C_{IN}$  and the output capacitor  $C_{OUT}$  is to reduce the input and output voltage ripples. Experimentation is usually necessary to determine their value. The rated DC voltage of capacitors used should be higher than the maximum DC voltage applied.

Owing to the concern of product lifetime, ceramic capacitors are recommended. But ceramic capacitors with high rated DC voltage and high capacitance are rare in general. Multiple capacitors connecting in parallel can be used for  $C_{\text{IN}}$  and  $C_{\text{OUT}}$ . In this example, two 10  $\mu\text{F}$  25V ceramic capacitor are used for  $C_{\text{IN}}$ , and two 2.2  $\mu\text{F}$  100V ceramic capacitor are used for  $C_{\text{OUT}}$ .



www.ti.com PC Board Layout

 $C_{\text{VCC}}$ : The capacitor on the VCC pin provides noise filtering and stabilizes the LDO regulator. It also prevents false triggering of the VCC UVLO.  $C_{\text{VCC}}$  is recommended to be a 1  $\mu\text{F}$  good quality and low ESR ceramic capacitor.

 $C_{\text{CDHC}}$ : The capacitor at the CDHC pin mainly determines the soft-start time  $t_{SS}$ , i.e. the time for the output voltage to reach its maximum.  $t_{SS}$  is determined from the following equation:

$$t_{SS} = \frac{C_{CDHC} \times 2.25V}{120 \ \mu A} \tag{7}$$

In this example, C<sub>CDHC</sub> is recommended to be a 0.47 µF good quality and low ESR ceramic capacitor.

 $R_{RT}$  and  $R_{IREF}$ : The resistors  $R_{RT}$  and  $R_{IREF}$  set the switching frequency  $f_{SW}$  of the boost converter and the LED current  $I_{LED}$  respectively. From the LM3492HC datasheet,  $R_{RT}$  is selected to be 274 k $\Omega$  if  $f_{SW}$  is 500 kHz (Figure 3), and  $R_{IREF}$  is selected to be 8.25 k $\Omega$  if  $I_{LED}$  is 150 mA (Figure 4).

 $R_{COMM}$ : Since the COMM pin is open drain, a resistor  $R_{COMM}$  of 52.3 k $\Omega$  is used to connect the VCC and COMM pins to implement a pull-up function.

## 4 PC Board Layout

The layout of the printed circuit board is critical to optimize the performance of the LM3492HC application circuit. In general, external components should be placed as close to the LM3492HC and each other as possible in order to make copper traces short and direct. In particular, components of the boost converter  $C_{\text{IN}}$ ,  $L_1$ ,  $D_1$ ,  $C_{\text{OUT}}$ , and the LM3492HC should be closed. Also, the output feedback capacitor  $C_{\text{FB1}}$  should be closed to the output capacitor  $C_{\text{OUT}}$ . The ground plane connecting the GND, PGND, and LGND pins and the exposed pad of the LM3492HC and the ground connection of the  $C_{\text{IN}}$  and  $C_{\text{OUT}}$  should be placed on the same copper layer.

Good heat dissipation helps optimize the performance of the LM3492HC. The ground plane should be used to connect the exposed pad of the LM3492HC, which is internally connected to the LM3492HC die substrate. The area of the ground plane should be extended as much as possible on the same copper layer around the LM3492HC. Using numerous vias beneath the exposed pad to dissipate heat of the LM3492HC to another copper layer is also a good practice.



Bill of Materials www.ti.com

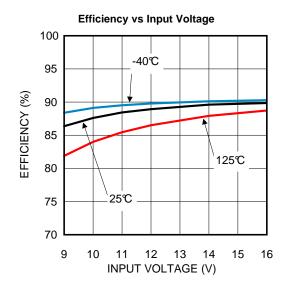
# 5 Bill of Materials

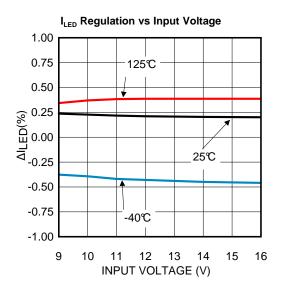
Item	Part Number	Mfg name	Part Description	Qty	Ref Designator(s)	Size
1	GRM31CR61E106KA12L	muRata	Cap 10 μF 25V X5R	2	C <sub>IN1</sub> , C <sub>IN2</sub>	1206
2	GRM188R71C474KA88D	muRata	0603/X7R/0.47 μF/16V	1	C <sub>CDHC</sub>	0603
3	GRM1885C2A100JA01D	muRata	0603/COG/10 pF/100V	1	C <sub>FB1</sub>	0603
4	GRM188R71C105KA12D	muRata	0603/X7R/1 μF/16V	1	C <sub>vcc</sub>	0603
5	GRM32ER72A225KA35L	muRata	Cap 2.2uF 100V X7R	2	C <sub>O1</sub> , C <sub>O2</sub>	1210
6	CRCW060352K3FKEA	Vishay	Resistor Chip 52.3 kΩ 1%	1	R <sub>COMM</sub>	0603
7	CRCW0603274KFKEA	Vishay	Resistor Chip 274 kΩ 1%	1	R <sub>RT</sub>	0603
8	CRCW0603309KFKEA	Vishay	Resistor Chip 309 kΩ 1%	1	R <sub>FB1</sub>	0603
9	CRCW060316K2FKEA	Vishay	Resistor Chip 16.2 kΩ 1%	1	R <sub>FB2</sub>	0603
10	CRCW06038K25FKEA	Vishay	Resistor Chip 8.25 kΩ 1%	1	R <sub>IREF</sub>	0603
11	CRCW06030000Z0EA	Vishay	Resistor Chip 0Ω 1%	1	R <sub>ILIM0</sub>	0603
12	CDRH10D68/ANP- 270MC	Sumida	Inductor 27 µH 1.9A	1	L <sub>1</sub>	10×10×6.8
13	SK310A-TP	Micro Commercial	Schottky 100V 3A	1	D <sub>1</sub>	SMA
14	1502-2k-ND	KEYSTONE	Terminal DBL Turret 0.109"L Brass	11	VIN, GND, PGND, VLED1, VLED2, IOUT1, IOUT2, DIM1, DIM2, COMM, EN	
15	LM3492HC	TI	LM3492HC Evaluation Board	1	PCB	
16	LM3492HC	TI	IC LM3492HC	1	U1	HTSSOP-20

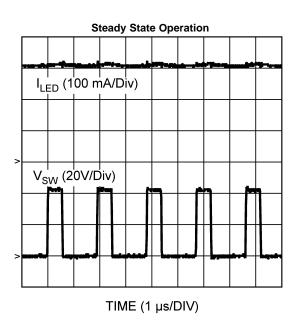


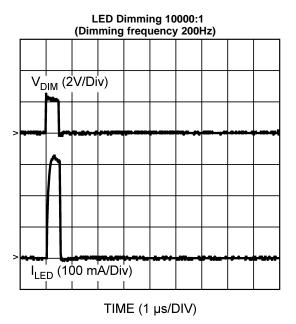
# **6** Typical Performance and Waveforms

All curves and waveforms taken at  $V_{IN}$  = 12V with the evaluation board and  $T_A$  = 25°C unless otherwise specified.

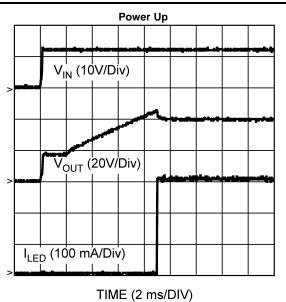


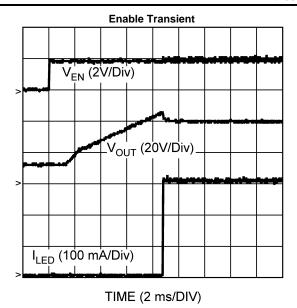












#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

## Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID www.ti-rfid.com

OMAP Applications Processors <a href="www.ti.com/omap">www.ti.com/omap</a> TI E2E Community <a href="e2e.ti.com">e2e.ti.com</a>

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>